



VMDSEMI

VFTP010R039NA

Datasheet



VMDSEMI

General Description

Symbol

| | | |
|---------------|--------------------|-------|
| $V_{(BR)DSS}$ | $R_{DS(ON)_{max}}$ | I_D |
| 100V | 3.9mΩ@10V | 120A |

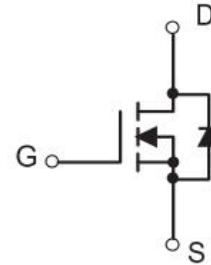


Figure 1 Symbol of VFTP010R039NA

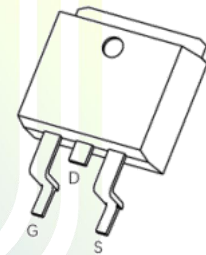
Features

- High Power and current handing capability
- Load switch
- High density cell design for ultra low $R_{DS(ON)}$
- Lead free product is acquired

Application

- SMPS and general purpose applications
- Hard switched and high frequency circuits

Package Type



TO-263-2L

Figure 2 Package Type of VFTP010R039NA

Ordering Information

| Product Name | Package |
|---------------|-----------|
| VFTP010R039NA | TO-263-2L |

Absolute Maximum Ratings ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Rating | Unit |
|---|-----------|------------|------------------|
| Drain-Source Voltage | V_{DSS} | 100 | V |
| Gate-Source Voltage | V_{GSS} | ± 20 | V |
| Continuous Drain Current ^{Note1} | I_D | 120 | A |
| Pulsed Drain Current ^{Note2} | I_{DM} | 480 | |
| Avalanche Current ^{Note3} | I_{AS} | 28 | |
| Single Pulsed Avalanche Energy ^{Note3} | E_{AS} | 392 | mJ |
| Total Power Dissipation ^{Note5} | P_D | 227 | W |
| Junction Temperature | T_J | 150 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | -55 to 150 | $^\circ\text{C}$ |

Thermal Resistance

| Parameter | Symbol | Min | Typ | Max | Unit |
|--|-----------------|-----|------|-----|---------------------------|
| Thermal Resistance, Junction-to-Ambient ^{Note6} | $R_{\theta JA}$ | | 62 | | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | | 0.55 | | $^\circ\text{C}/\text{W}$ |

Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|--|--------------|-------------------------------|-----|------|-----------|---------|
| Statistic Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 100 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=100V, V_{GS}=0V$ | | | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS}=0V$ | | | ± 100 | nA |
| Gate Threshold Voltage ^{Note4} | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2.0 | 3.0 | 4.0 | V |
| Static Drain-Source On-Resistance ^{Note4} | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=20A$ | | 3.0 | 3.9 | mΩ |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{ISS} | $V_{DS}=45V$ | | 5551 | | pF |
| Output Capacitance | C_{OSS} | $V_{GS}=0V$ | | 1591 | | pF |
| Reverse Transfer Capacitance | C_{RSS} | $f=1MHz$ | | 60 | | pF |
| Total Gate Charge | Q_g | $V_{DS}=50V$ | | 115 | | nC |
| Gate-Source Charge | Q_{gs} | $V_{GS}=10V$ | | 38 | | |
| Gate-Drain Charge | Q_{gd} | $I_D=20A$ | | 30 | | |
| Switching Parameters | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=50V$ | | 45 | | ns |
| Turn-on Rise Time | t_r | $V_{GS}=10V$ | | 59 | | |
| Turn-off Delay Time | $t_{d(off)}$ | $I_D=20A$ | | 70 | | |
| Turn-off Fall Time | t_f | $R_G=3.3\Omega$ | | 31 | | |
| Diode Characteristics | | | | | | |
| Diode Forward Voltage ^{Note4} | V_{SD} | $V_{GS}=0V, I_S=20A$ | | | 1.2 | V |
| Continuous Source Current | I_S | | | | 120 | A |
| Pulsed Source Current | I_{SM} | | | | 480 | |

Notes :

1. The maximum current rating is limited by package. And device mounted on a large heatsink.
2. Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
3. EAS condition: $V_{DD} = 50V, V_{GS} = 10V, L = 1.0mH$ Starting $T_J = 25^\circ C$.
4. Pulse Test : Pulse Width $\leq 380\mu s$, duty cycle $\leq 2\%$.
5. The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ C$. And device mounted on a large heatsink
6. Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$.

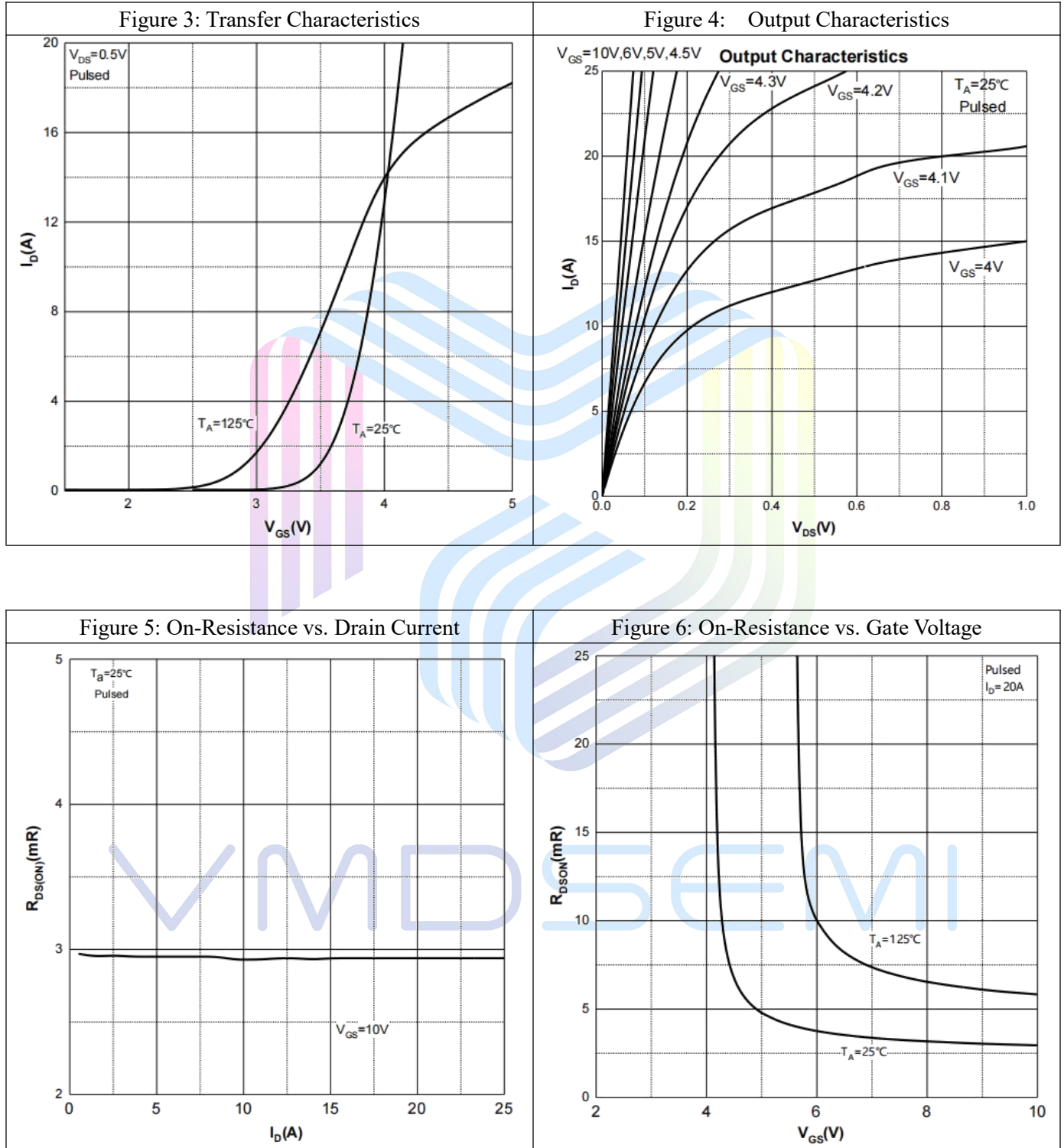
Typical Performance Characteristics


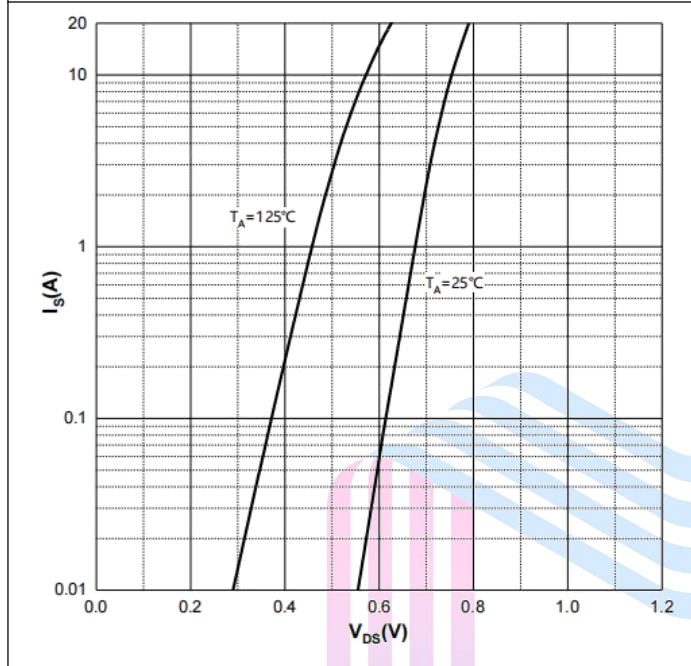
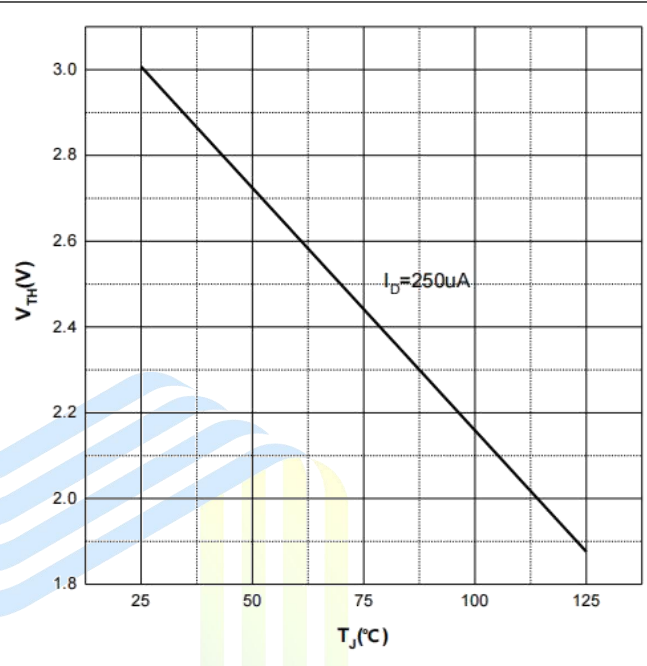
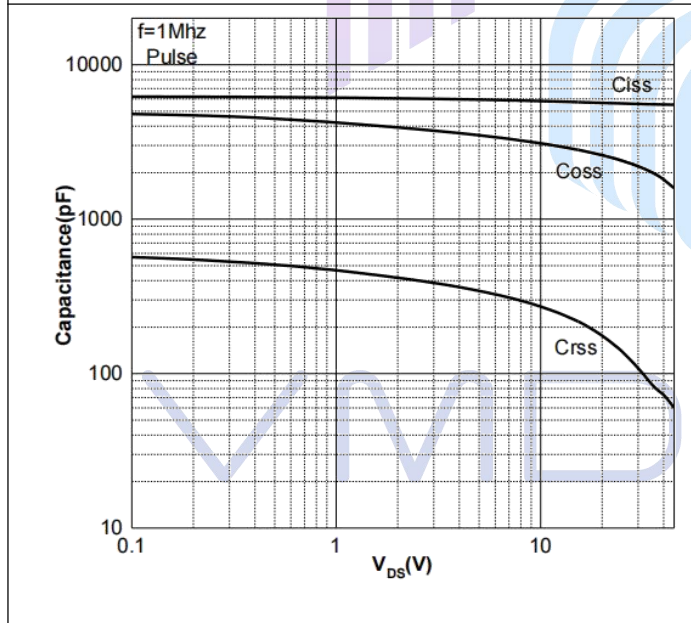
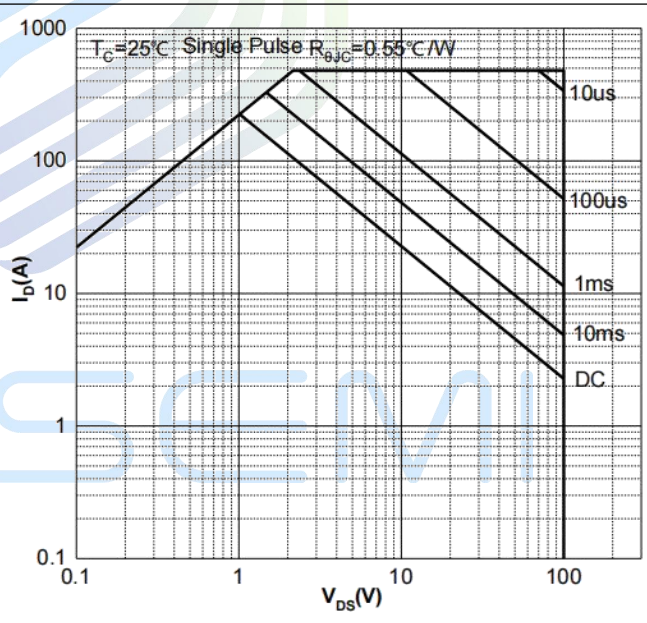
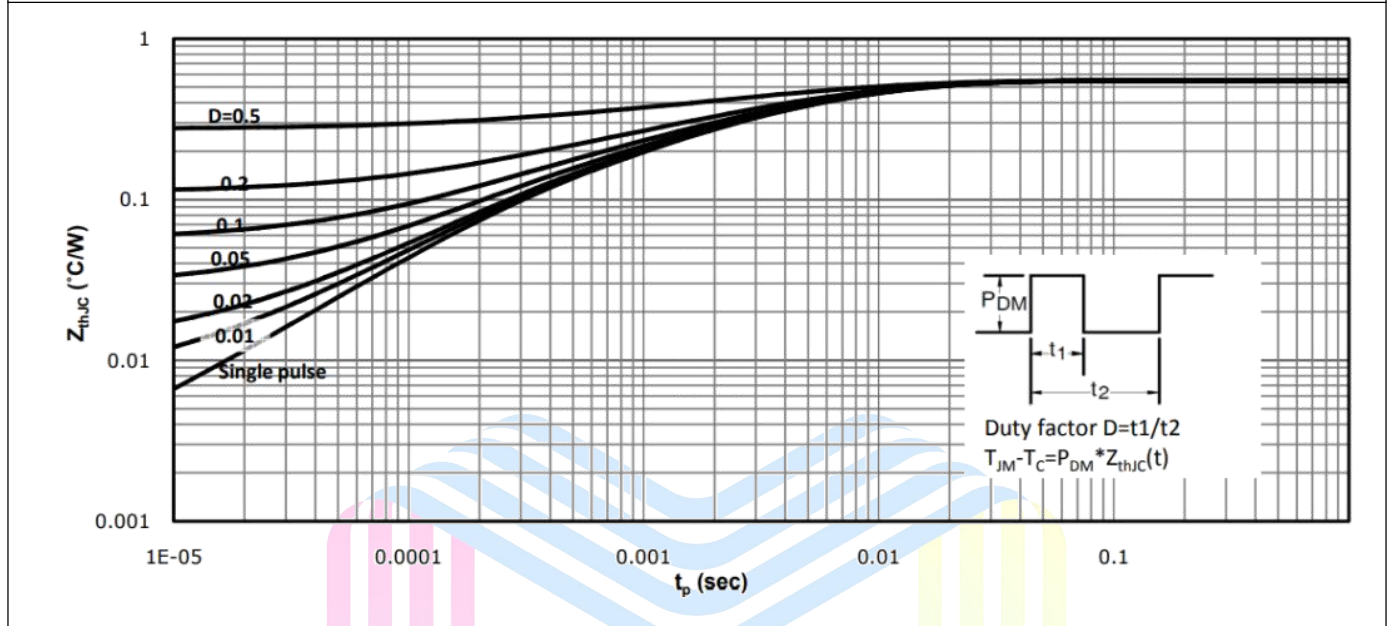
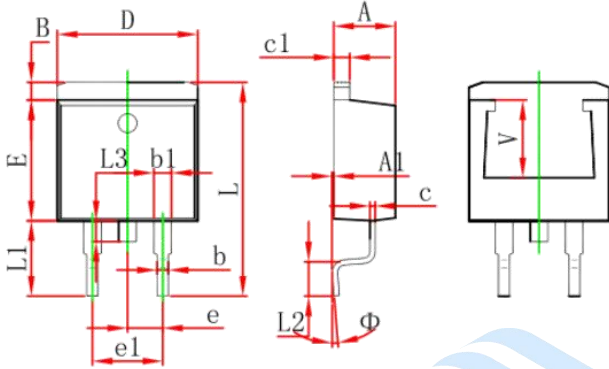
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance




Mechanical Dimensions:
TO-263-2L Package Information


| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.470 | 4.670 | 0.176 | 0.184 |
| A1 | 0.000 | 0.150 | 0.000 | 0.006 |
| B | 1.120 | 1.420 | 0.044 | 0.056 |
| b | 0.710 | 0.910 | 0.028 | 0.036 |
| b1 | 1.170 | 1.370 | 0.046 | 0.054 |
| c | 0.310 | 0.530 | 0.012 | 0.021 |
| c1 | 1.170 | 1.370 | 0.046 | 0.054 |
| D | 10.010 | 10.310 | 0.394 | 0.406 |
| E | 8.500 | 8.900 | 0.335 | 0.350 |
| e | 2.540 TYP. | | 0.100 TYP. | |
| e1 | 4.980 | 5.180 | 0.196 | 0.204 |
| L | 14.940 | 15.500 | 0.588 | 0.610 |
| L1 | 4.950 | 5.450 | 0.195 | 0.215 |
| L2 | 2.340 | 2.740 | 0.092 | 0.108 |
| L3 | 1.300 | 1.700 | 0.051 | 0.067 |
| Φ | 0° | 8° | 0° | 8° |
| V | 5.600 REF. | | 0.220REF. | |

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